
RZ/G2L, G2LC, G2UL, G3S, G3E, RZ/V2L, V2H, V2N, RZ/N2H, RZ/T2H**Release Note for RZ Multi-OS Package V4.2.0**

Introduction

This is the release note for RZ Multi-OS Package v4.2.0

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1. Overview

This release note describes what's additionally supported, improvements and bug fixes in RZ Multi-OS Package v4.2.0.

2. Proven Environment

Dependent tools and software	Detail
Integrated Development Environment (IDE)	e2 studio 2026-07
IAR EWARM FSP Smart Configurator I-jet Debug probe	9.60.3 2026-07
GC cross-toolchain	Arm GNU Toolchain : 13.3.1.arm-13-24 GCC ARM A-Profile (AArch64 bare-metal) 13.2.Rel1
Segger J-Link Software	V9.44 V7.96e
RZ/G Verified Linux Package	VLP/G v3.0.7-update5 URL: RZ/G Verified Linux Package [5.10-CIP] Renesas VLP/G v4.0.1 URL: RZ MPU Verified Linux Package [6.1-CIP] Renesas
RZ/G3E Linux BSP	RZ/G3E Linux BSP v1.0.0
RZ/V Verified Linux Package	VLP/V v3.0.7-update5 URL: RZ/V Verified Linux Package [5.10-CIP] Renesas VLP/V v4.0.1 URL: RZ MPU Verified Linux Package [6.1-CIP] Renesas
RZ/V AI Software Development Kit (SDK)	RZ/V2H AI SDK v6.0.0 RZ/V2N AI SDK v6.3.0
RZ/T Verified Linux Package RZ/N Verified Linux Package	VLP v5.0.0 URL: RZ MPU Verified Linux Package [6.12-CIP] Renesas
Flexible Software Package (FSP)	RZ FSP v4.2.0

3. Supported RZ MPU Kits

RZ Multi-OS Package v4.2.0 works with the kits listed below:

- [RZ/G2L Evaluation Board Kit](#)
- [RZ/G2LC Evaluation Board Kit](#)
- [RZ/G2UL Evaluation Board Kit](#)
- [RZ/G3S Evaluation Board Kit](#)
- [RZ/G3E Evaluation Board Kit](#)
- [SMARC SOM Evaluation Kit for RZ/V2L MPU with AI Accelerator](#)
- [RZ/V2H Quad-core Version AI MPU Evaluation Kit](#)
- [RZ/V2N Quad-core Version AI MPU Evaluation Kit](#)
- [RZ/N2H Evaluation Board Kit](#)
- [RZ/T2H Evaluation Board Kit](#)

4. New Features

- Updated to align with RZ FSP Version 4.2.0.
- Added CR8_core0-CR8_core1 inter-core communication example project for RZ/V2H.
- SBOM support.

5. Fixes and Improvements

- Improve performance to RZ/T-N BL2 boot

6. Known Issues

- RZ/G VLP v3.0.7 and RZ/V VLP v3.0.7, enabling Docker during the build process will cause the RPMsg demo to display a warning on the RZ/G2x and RZ/G3S boards.

```
metal: warning: metal_linux_irq_handling: Failed to set scheduler: -1
```

Cause: Docker restricts real-time priority assignment, causing libmetal to fail setting real-time scheduling.

Impact: RPMsg still works, but interrupt handling performance may degrade.

Workaround1: When building a Linux BSP, skip the optional step to enable Docker.

Workaround2: You can allow real-time scheduling by executing the following command:

```
echo -1 > /proc/sys/kernel/sched_rt_runtime_us
```

However, allowing real-time scheduling can cause certain processes to take up extreme CPU time. If you want to allow real-time scheduling, please do so after sufficient evaluation.

- When building Yocto with VLP v3.0.7-update5, the OpenSSH source may be outdated, which can cause build errors.

In such cases, please ensure that the following patch has been applied to your Yocto recipe.

<https://github.com/renesas-rz/meta-renesas/commit/4c8a279abac290906da0bcf2a711f31fae1f17a8.patch>

- When running the RZ/V2H rpmmsg example on environment with CA55, CR8 core0, and CR8 core1, it is necessary to downgrade the J-Link DLL to version 7.96e.

For details, please refer to Section 4.7 of the RZ/V2H Quick Start Guide for RZ Multi-OS Package (R01QS0077) included in this package.

- When using the RemoteProc example of the RZ/T2H and RZ/N2H, EFI support must be disabled in U-Boot. This requirement avoids memory reservation conflicts with the reserved-memory regions used by the RemoteProc example. As a result, EFI based boot flows are not supported when running the RemoteProc example.

7. Deprecations

None.

8. Third Party Software

- OpenAMP: [c4683284](#)
- libmetal: [2024.05.0](#)

Revision History

Rev.	Date	Description	
		Page	Summary
4.00	Mar.31.26	-	First edition issued Concatenate all the RZ Multi-OS Packages to RZ Multi-OS package. Updated to align with RZ FSP Version 4.0.0 Updated to align with RZ/V2N AI SDK V6.3.0 Updated AWO example project for S2R support
4.10	Jun.30.26	-	Updated to align with RZ FSP Version 4.1.0 Added remoteproc support for RZ/V2H CR8 core Updated to OpenAMP/libmetal version 2024.05
4.20	Sep.03.26	-	Updated to align with RZ FSP Version 4.2.0 Added CR8_core0-CR8_core1 inter-core communication example project for RZ/V2H. SBOM support

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power

-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

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